BCX54U

NPN Silicon Epitaxial Planar Power Transistor

Medium Power Transistor



1.Base 2.Collector 3.Emitter SOT-89 Plastic Package

Absolute Maximum Ratings ($T_a = 25$ °C)

Parameter	Symbol	Value	Unit	
Collector Base Voltage	V _{CBO}	45	V	
Collector Emitter Voltage	Vceo	45	V	
Emitter Base Voltage	V _{EBO}	5	V	
Collector Current	Ic	1	Α	
Peak Collector Current	Ісм	1.5	Α	
Peak Base Current	Івм	0.2	Α	
Total Power Dissipation	P _{tot}	0.5 ¹⁾ 1.3 ²⁾	W	
Junction Temperature	Tj	150	°C	
Storage Temperature Range	T _{stg}	- 55 to + 150	°C	

Thermal Characteristics

Parameter	Symbol	Max.	Unit	
Thermal Resistance from Junction to Ambient	R _{0JA}	250 ¹⁾ 96 ²⁾	°C/W	

¹⁾Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



²⁾Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

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Characteristics at $T_a = 25$ °C

Parameter	Symbol	Min.	Тур.	Max.	Unit	
DC Current Gain at $V_{CE} = 2 \text{ V}$, $I_C = 5 \text{ mA}$ at $V_{CE} = 2 \text{ V}$, $I_C = 150 \text{ mA}$ at $V_{CE} = 2 \text{ V}$, $I_C = 500 \text{ mA}$	BCX54-10U BCX54-16U	h _{FE} hFE hFE h _{FE}	63 63 100 40	- - -	- 160 250	- - -
Collector Base Cutoff Current at V _{CB} = 30 V		Ісво	-	-	100	nA
Emitter Base Cutoff Current at V _{EB} = 5 V		I _{EBO}	-	-	100	nA
Collector Base Breakdown Voltage at $I_C = 100 \mu A$		V _{(BR)CBO}	45	ı	-	٧
Collector Emitter Breakdown Voltage at I _C = 1 mA		V _{(BR)CEO}	45	-	-	V
Emitter Base Breakdown Voltage at I _E = 100 μA		V _{(BR)EBO}	5	-	-	V
Collector Emitter Saturation Voltage at I_C = 500 mA, I_B = 50 mA		V _{CE(sat)}	-	-	0.5	V
Base Emitter Saturation Voltage at I_C = 500 mA, I_B = 50 mA		V _{BE(sat)}	-	-	1.1	٧
Base Emitter Voltage at $V_{CE} = 2 \text{ V}$, $I_C = 500 \text{ mA}$		V_{BE}	-	-	1	V
Transition Frequency at $V_{CE} = 5 \text{ V}$, $I_C = 10 \text{ mA}$, $f = 100 \text{ MHz}$		f⊤	-	130	-	MHz



Electrical Characteristics Curves

Fig. 1 Output Characteristics Curve

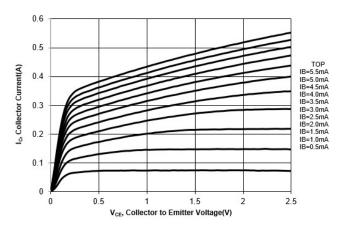


Fig. 2 Collector Current vs. Base to Emitter Voltage

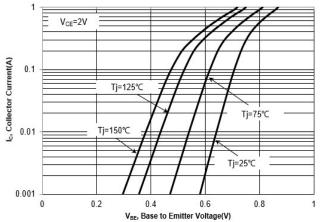


Fig. 3 hFE,DC Current Gain vs. Collector Current

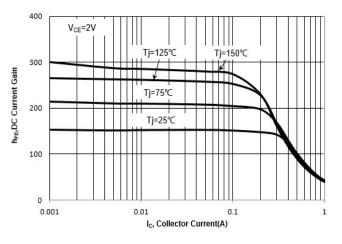
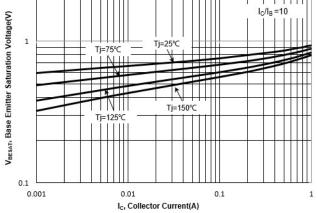


Fig. 4 V_{BE(sat)} vs. Collector Current





Electrical Characteristics Curves

Fig. 5 $V_{\text{CE(sat)}}$ vs. Collector Current

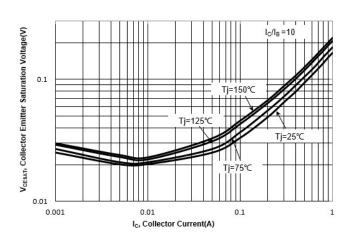


Fig. 6 Output Capacitance

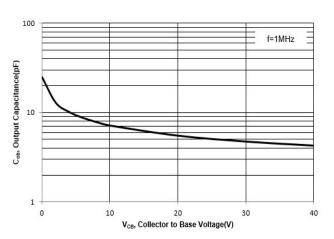
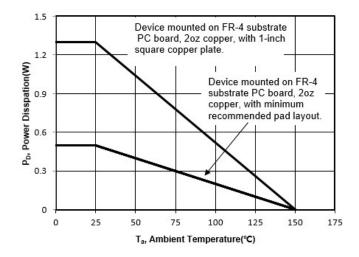


Fig 7. Power Derating Curve

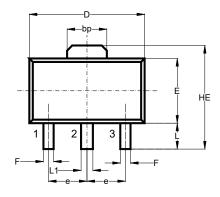


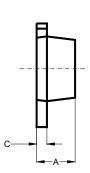


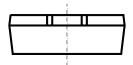
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Package Outline (Dimensions in mm)

SOT-89

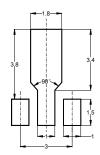






Unit	Α	bp	С	D	Е	F	HE	е	L	L1
m.m.	1.6	1.60	0.5	4.6	2.6	0.45	4.25	1.5	1.05	0.51
mm	1.4	1.50	0.3	4.4	2.4	0.35	3.75	typ.	0.95	0.41

Recommended Soldering Footprint



Packing information

	Tape Width	Pitch		Ree	el Size		
Package	Package (mm) mm		inch	mm	inch	Per Reel Packing Quantity	
207.22	40	0 . 0 4	0.045 + 0.004	178	7	1,000	
SOT-89	12	8 ± 0.1	0.315 ± 0.004	330	13	4,000	

Marking information

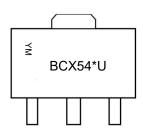
"BCX54*U" = Part No. (" * " = HFE grouping Code)

" YM " = Date Code Marking

" Y " = Year

" M " = Month

Font type: Arial



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